



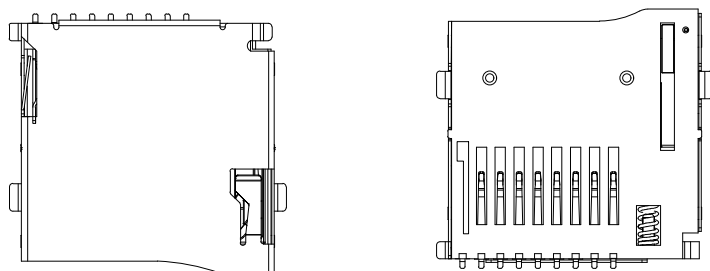
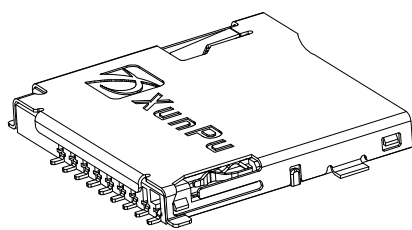
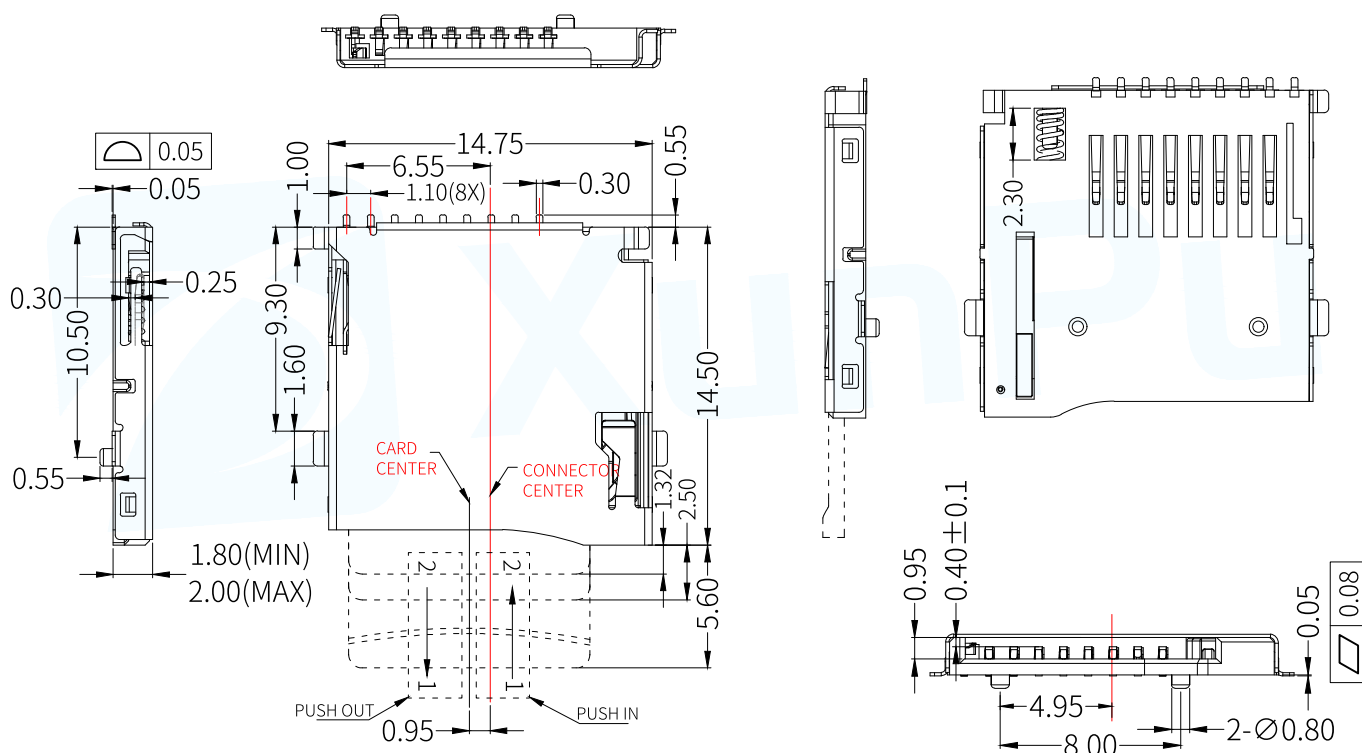
TF-115-BCP9
W14.50xD14.75xH1.80

PIN 数(Number of contacts) : 8+1PIN	耐电压(Withstand voltage) : 500V AC for 1 min
操作方式(Operation mode): 自弹式/PUSH PUSH	操作寿命(Operation life): 5,000 Cycles Min
温度范围(Operating temp): -40°C TO +85°C	焊接温度(Welding temperature): 260±5° 5s
额定负荷(Rated load): 0.5A PERP IN.	焊接方式(Welding mode): 贴片式/SMT
接触电阻(Contact resistance): 100mΩ max.	包装方式(Packaging method): 卷带/Tape & Reel (TR)
绝缘电阻(Insulation resistance): 1000MΩ min.	最小包装(Minimum packing): 1,000/PCS

外形尺寸 (UNIT:MM) / Size Chart

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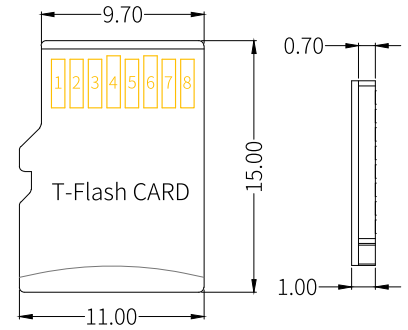
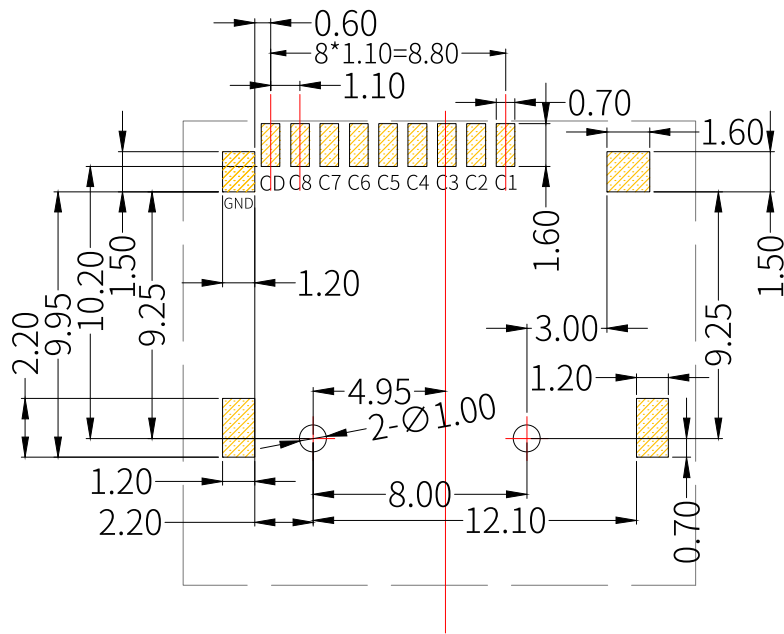
更多资料请参考技术选型档!



NOTES

- MATERIAL:**
Housing: High Temperature Thermoplastic UL94V-0, Color: Black.
Contact: Copper Alloys.
Shell: Copper Alloys Or Steel.
- PLATING:**
Underplate: Nickel.
Contact Area: Gold Over Nickel.
Solder Area: Tin Over Nickel.
- MULTIMEDIA CARD COMPATIBLE**

T-Flash CARD



引脚定义/Pin Definition

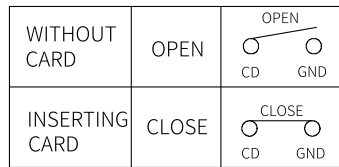
PIN#	NAME	TYPE	DESCRIPTION
C1	DAT2	I/O/PP	DATE LIN(BIT2)
C2	CD/DAT3	I/O/PP	CARD DETECT DATELIN(BIT3)
C3	CMD	PP	COMMAND RESPONSE
C4	VDD	S	SUPPLY VOLTAGE
C5	CLX	I	CLOCK
C6	VSS	S	SUPPLY VOLTAGE GROUND
C7	DAT0	I/O/PP	DATE LIN(BIT0)
C8	DAT1	I/O/PP	DATE LIN(BIT1)

PCB焊盘区(PAD AREA)

禁区(KEEP OUT AREA)

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

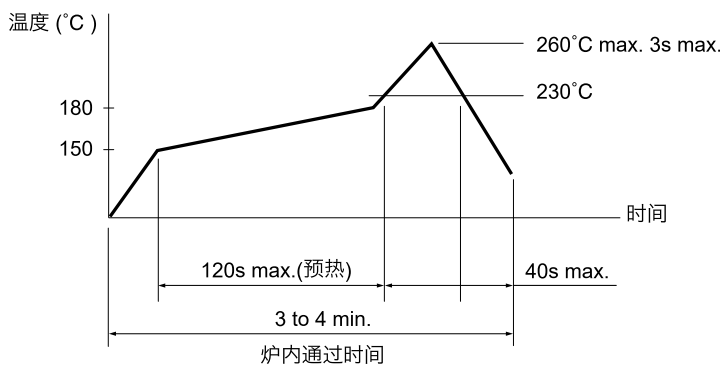
Circuit Diagram for Detect Switch



焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。